SCAS002A - D2957, JUNE 1987 - REVISED APRIL 1993

- Inputs Are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V<sub>CC</sub> and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

#### description

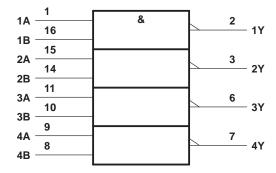
These devices contain four independent 2-input NAND gates. They perform the Boolean functions  $Y = \overline{A \cdot B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

The 54ACT11000 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The 74ACT11000 is characterized for operation from  $-40^{\circ}$ C to 85°C.

## FUNCTION TABLE (each gate)

INP	JTS	OUTPUT
Α	В	Y
Н	Н	L
L	Χ	Н
Х	L	Н

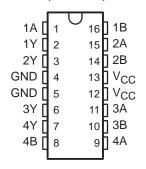
## logic symbol†



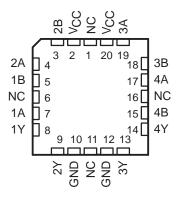
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

#### 54ACT11000 . . . J PACKAGE 74ACT11000 . . . D OR N PACKAGE (TOP VIEW)

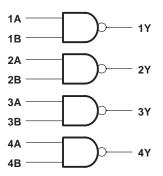


# 54ACT11000 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### logic diagram (positive logic)



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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

#### recommended operating conditions

		54ACT	11000	74ACT	11000	UNIT
		MIN	MAX	MIN	MAX	UNII
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ı	Input voltage	0	VCC	0	VCC	V
VO	Output voltage	0	Vcc	0	Vcc	V
IOH	High-level output current		-24		-24	mA
loL	Low-level output current		24		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	0	10	ns/V
TA	Operating free-air temperature	-55	125	- 40	85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	T,	<sub>Δ</sub> = 25°C	;	54AC	Γ11000	74ACT	11000	UNIT	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
	Jan - 50	4.5 V	4.4			4.4		4.4			
	ΙΟΗ = – 50 μΑ	5.5 V	5.4			5.4		5.4			
Vou	Jan - 24 mA	4.5 V	3.94			3.7		3.8		V	
VOH	IOH = - 24 mA	5.5 V	4.94			4.7		4.8		V	
	$I_{OH} = -50 \text{ mA}^{\ddagger}$	5.5 V				3.85					
	I <sub>OH</sub> = -75 mA <sup>‡</sup>	5.5 V						3.85			
	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1		0.1		
	ΙΟΣ = 30 μΑ	5.5 V			0.1		0.1		0.1		
Voi	lo 24 mΛ	4.5 V			0.36		0.5		0.44	V	
VOL	IOL = 24 mA	5.5 V			0.36		0.5		0.44		
	$I_{OL} = 50 \text{ mA}^{\ddagger}$	5.5 V					1.65			1	
	$I_{OL} = 75 \text{ mA}^{\ddagger}$	5.5 V							1.65		
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ	
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μΑ	
ΔI <sub>CC</sub> §	One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V			0.9		1		1	mA	
Ci	$V_I = V_{CC}$ or GND	5 V		3.5						pF	

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

<sup>§</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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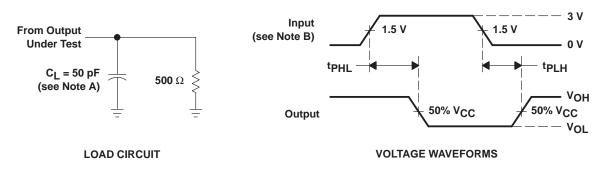
# switching characteristics over recommended ranges of supply voltage and free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	4 = 25°C	;	54ACT	11000	74ACT	11000	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
t <sub>PLH</sub>	A or B	V	1.5	7.2	10.9	1.5	13.3	1.5	12.3	
<sup>t</sup> PHL	AUIB	Y	1.5	5.8	8	1.5	9.5	1.5	8.8	ns

### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	23	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	. ,	,,			, ,	(4)	(5)		
74ACT11000D	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	-40 to 85	ACT11000
74ACT11000DR	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11000
74ACT11000DR.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11000
74ACT11000N	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	74ACT11000N
74ACT11000N.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	74ACT11000N

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

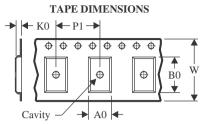
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT11000DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 23-May-2025



#### \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	74ACT11000DR	SOIC	D	16	2500	340.5	336.1	32.0	

## **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT11000N	N	PDIP	16	25	506	13.97	11230	4.32
74ACT11000N	N	PDIP	16	25	506	13.97	11230	4.32
74ACT11000N.A	N	PDIP	16	25	506	13.97	11230	4.32
74ACT11000N.A	N	PDIP	16	25	506	13.97	11230	4.32

## D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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